

Bond-Ply® 800

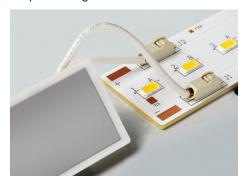
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PRODUCT DESCRIPTION

Thermally Conductive, Fiberglass Reinforced Pressure Sensitive Adhesive Tape

FEATURES AND BENEFITS

- Thermal impedance: 0.60°C-in²/W (@50 psi)
- High bond strength to most epoxies and metals
- Double-sided, pressure sensitive adhesive tape
- High performance, thermally conductive acrylic adhesive
- More cost-effective than heat-cure adhesive, screw mounting or clip mounting



Bond-Ply® 800 is a thermally conductive, electrically isolating double-sided tape.

Bond-Ply® 800 is utilized in lighting applications that require thermal transfer and electric isolation. High bond strengths obtained at ambient temperature lead to significant processing cost savings in labor, materials and throughput due to the elimination of mechanical fasteners and high temperature curing.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF BOND-PLY 800						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Gray		Gray		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.005, 0.008		0.127, 0.203		ASTM D374	
Elongation (%, 45° to Warp & Fill)	70		70		ASTM D412	
Tensile Strength (psi) / (MPa)	1500		10		ASTM D412	
CTE (um/m-°C), -40°C to +125°C	600		600		ASTM D3386	
Continuous Use Temp (°F) / (°C)	-40 to 257		-40 to 125		_	
ADHESION						
Lap Shear @ RT (psi) / (MPa) (1)	150		1.0		ASTM D1002	
ELECTRICAL			VALUE		TEST METHOD	
Dielectric Breakdown Voltage (Vac), 0.005			4000		ASTM D149	
Dielectric Breakdown Voltage (Vac), 0.008			6000		ASTM D149	
Dielectric Constant (1000 Hz)			4.0		ASTM D150	
Volume Resistivity (Ohm-meter)			1011		ASTM D257	
Flame Rating			V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K)			0.8		ASTM D5470	
THERMAL PERFORMANCE vs PR	ESSURE					
Initial Assembly Pressure (psi for 5 seconds)		10	25	50	100	200
TO-220 Thermal Performance (°C/W), 0.005		5.0	5.0	4.8	4.3	4.2
TO-220 Thermal Performance (°C/W), 0.008		6.2	6.0	5.6	5.3	5.2
Thermal Impedance (°C-in²/W), 0.005 (2)		0.63	0.62	0.60	0.58	0.57
Thermal Impedance (°C-in²/W), 0.008 (2)		0.78	0.74	0.72	0.71	0.71

¹⁾ Tested per ASTM D1002 with aluminum lap shear samples, 75 psi applied for 5 seconds then pressure removed. 0.5 square inch Bond-Ply 800 sample.

2) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These

TYPICAL APPLICATIONS INCLUDE

- · Mount LED assembly to troffer housing
- · Mount LED assembly to heat sink
- Mount heat spreader onto power converter PCB or onto motor control PCB
- Mount heat sink to BGA graphic processor or drive processor

CONFIGURATIONS AVAILABLE

Sheet form, roll form and die-cut parts



The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These
values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and
pressure applied.

Disclaimer

Note:

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Reference 0.1